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Details

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Product Status	Active
Core Processor	HCS12X
Core Size	16-Bit
Speed	40MHz
Connectivity	CANbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	91
Program Memory Size	64KB (64K × 8)
Program Memory Type	FLASH
EEPROM Size	·
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.72V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	112-LQFP
Supplier Device Package	112-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=s9s12xs64j1mal

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1.2 Signal Description

This section describes signals that connect off-chip. It includes a pinout diagram, a table of signal properties, and detailed discussion of signals. It is built from the signal description sections of the individual IP blocks on the device.

1.2.1 Device Pinout

The XS family of devices offers pin-compatible packaged devices to assist with system development and accommodate expansion of the application.

The S12XS family devices are offered in the following package options:

- 112-pin LQFP
- 80-pin QFP
- 64-pin LQFP



Device Overview S12XS Family



3.1.1 Terminology

Table 3-1. Acronyms and Abbreviations

Logic level "1"	Voltage that corresponds to Boolean true state
Logic level "0"	Voltage that corresponds to Boolean false state
0x	Represents hexadecimal number
x	Represents logic level 'don't care'
Byte	8-bit data
word	16-bit data
local address	based on the 64KB Memory Space (16-bit address)
global address	based on the 8MB Memory Space (23-bit address)
Aligned address	Address on even boundary
Mis-aligned address	Address on odd boundary
Bus Clock	System Clock. Refer to CRG Block Guide.
single-chip modes	Normal Single-Chip Mode
	Special Single-Chip Mode
normal modes	Normal Single-Chip Mode
special modes	Special Single-Chip Mode
NS	Normal Single-Chip Mode
SS	Special Single-Chip Mode
Unimplemented areas	Areas which are accessible by the pages (RPAGE, PPAGE, EPAGE) and not implemented
PRR	Port Replacement Registers
PRU	Port Replacement Unit located on the emulator side
MCU	MicroController Unit
NVM	Non-volatile Memory; Flash, Data FLASH or ROM
IFR	Information Row sector located on the top of NVM. For Test purposes.

3.1.2 Features

The main features of this block are:

- Paging capability to support a global 8MB memory address space
- Bus arbitration between the masters CPU, BDM
- Simultaneous accesses to different resources¹ (internal, and peripherals) (see Figure 3-1)
- Resolution of target bus access collision
- MCU operation mode control
- MCU security control
- Separate memory map schemes for each master CPU, BDM
- ROM control bits to enable the on-chip FLASH or ROM selection
- Generation of system reset when CPU accesses an unimplemented address (i.e., an address which does not belong to any of the on-chip modules) in single-chip modes

1. Resources are also called targets.



Memory Mapping Control (S12XMMCV4)

3.3.2.1 Mode Register (MODE)

Address: 0x000B PRR



Figure 3-3. Mode Register (MODE)

Read: Anytime. Write: Only if a transition is allowed (see Figure 3-5).

The MODE bits of the MODE register are used to establish the MCU operating mode.

Table	3-3.	MODE	Field	Descriptions
-------	------	------	-------	--------------

Field	Description
7 MODC	Mode Select Bit — This bit controls the current operating mode during RESET high (inactive). The external mode pin MODC determines the operating mode during RESET low (active). The state of the pin is latched into the respective register bit after the RESET signal goes inactive (see Figure 3-3).
	Write restrictions exist to disallow transitions between certain modes. Figure 3-5 illustrates all allowed mode changes. Attempting non authorized transitions will not change the MODE bits, but it will block further writes to these register bits except in special modes.
	Write accesses to the MODE register are blocked when the device is secured.



Transition done by external pins (MODC)



Transition done by write access to the MODE register



Figure 3-5. Mode Transition Diagram when MCU is Unsecured



Background Debug Module (S12XBDMV2)



Figure 5-9. BDM Target-to-Host Serial Bit Timing (Logic 1)





SEC[1:0] = '10'. All other combinations put the device in a secured mode. The recommended value to put the device in secured state is the inverse of the unsecured state, i.e. SEC[1:0] = '01'.

SEC[1:0]	Security State
00	1 (secured)
01	1 (secured)
10	0 (unsecured)
11	1 (secured)

Tahla	7_/	Security	Rite
lable	7-4.	Security	DILS

NOTE

Please refer to the Flash block guide for actual security configuration (in section "Flash Module Security").

7.1.4 Operation of the Secured Microcontroller

By securing the device, unauthorized access to the EEPROM and Flash memory contents can be prevented. However, it must be understood that the security of the EEPROM and Flash memory contents also depends on the design of the application program. For example, if the application has the capability of downloading code through a serial port and then executing that code (e.g. an application containing bootloader code), then this capability could potentially be used to read the EEPROM and Flash memory contents even when the microcontroller is in the secure state. In this example, the security of the application could be enhanced by requiring a challenge/response authentication before any code can be downloaded.

Secured operation has the following effects on the microcontroller:



S12XE Clocks and Reset Generator (S12XECRGV1)

- System Reset generation from the following possible sources:
 - Power on reset
 - Low voltage reset
 - Illegal address reset
 - COP reset
 - Loss of clock reset
 - External pin reset
- Real-Time Interrupt (RTI)

8.1.2 Modes of Operation

This subsection lists and briefly describes all operating modes supported by the S12XECRG.

• Run Mode

All functional parts of the S12XECRG are running during normal Run Mode. If RTI or COP functionality is required the individual bits of the associated rate select registers (COPCTL, RTICTL) have to be set to a non zero value.

• Wait Mode

In this mode the IPLL can be disabled automatically depending on the PLLWAI bit.

• Stop Mode

Depending on the setting of the PSTP bit Stop Mode can be differentiated between Full Stop Mode (PSTP = 0) and Pseudo Stop Mode (PSTP = 1).

— Full Stop Mode

The oscillator is disabled and thus all system and core clocks are stopped. The COP and the RTI remain frozen.

Pseudo Stop Mode

The oscillator continues to run and most of the system and core clocks are stopped. If the respective enable bits are set the COP and RTI will continue to run, else they remain frozen.

Self Clock Mode

Self Clock Mode will be entered if the Clock Monitor Enable Bit (CME) and the Self Clock Mode Enable Bit (SCME) are both asserted and the clock monitor in the oscillator block detects a loss of clock. As soon as Self Clock Mode is entered the S12XECRG starts to perform a clock quality check. Self Clock Mode remains active until the clock quality check indicates that the required quality of the incoming clock signal is met (frequency and amplitude). Self Clock Mode should be used for safety purposes only. It provides reduced functionality to the MCU in case a loss of clock is causing severe system conditions.

8.1.3 Block Diagram

Figure 8-1 shows a block diagram of the S12XECRG.

Analog-to-Digital Converter (ADC12B16CV1)

10.3.2.10 ATD Input Enable Register (ATDDIEN)



Read: Anytime

Write: Anytime

Table 10-20. ATDDIEN Field Descriptions

Field	Description
15–0 IEN[15:0]	 ATD Digital Input Enable on channel x (x= 15, 14, 13, 12, 11, 10, 9, 8, 7, 6, 5, 4, 3, 2, 1, 0) — This bit controls the digital input buffer from the analog input pin (ANx) to the digital data register. 0 Disable digital input buffer to ANx pin 1 Enable digital input buffer on ANx pin. Note: Setting this bit will enable the corresponding digital input buffer continuously. If this bit is set while simultaneously using it as an analog port, there is potentially increased power consumption because the digital input buffer maybe in the linear region.

10.3.2.11 ATD Compare Higher Than Register (ATDCMPHT)

Writes to this register will abort current conversion sequence.

Read: Anytime

Write: Anytime

Module Base + 0x000E



Table 10-21. ATDCMPHT Field Descriptions

Field	Description
15–0	Compare Operation Higher Than Enable for conversion number <i>n</i> (<i>n</i> = 15, 14, 13, 12, 11, 10, 9, 8, 7, 6, 5,
CMPHT[15:0]	4, 3, 2, 1, 0) of a Sequence — This bit selects the operator for comparison of conversion results.
	0 If result of conversion <i>n</i> is lower or same than compare value in ATDDR <i>n</i> , this is flagged in ATDSTAT2
	1 If result of conversion <i>n</i> is higher than compare value in ATDDR <i>n</i> , this is flagged in ATDSTAT2



Freescale's Scalable Controller Area Network (S12MSCANV3)

11.1.1 Glossary

ACK	Acknowledge of CAN message				
CAN	Controller Area Network				
CRC	Cyclic Redundancy Code				
EOF	End of Frame				
FIFO	First-In-First-Out Memory				
IFS	Inter-Frame Sequence				
SOF	Start of Frame				
CPU bus	CPU related read/write data bus				
CAN bus	CAN protocol related serial bus				
oscillator clock	Direct clock from external oscillator				
bus clock	CPU bus related clock				
CAN clock	CAN protocol related clock				

Table 11-2. Terminology

11.1.2 Block Diagram



Figure 11-1. MSCAN Block Diagram



	MSCAN Mode						
CPU Mode		Reduced Power Consumption					
	Normal	Sleep Power Down		Disabled (CANE=0)			
RUN	CSWAI = X ⁽¹⁾ SLPRQ = 0 SLPAK = 0	CSWAI = X SLPRQ = 1 SLPAK = 1		CSWAI = X SLPRQ = X SLPAK = X			
WAIT	CSWAI = 0 SLPRQ = 0 SLPAK = 0	CSWAI = 0 SLPRQ = 1 SLPAK = 1	CSWAI = 1 SLPRQ = X SLPAK = X	CSWAI = X SLPRQ = X SLPAK = X			
STOP			CSWAI = X SLPRQ = X SLPAK = X	CSWAI = X SLPRQ = X SLPAK = X			

Table 11-38. CPU vs. MSCAN Operating Modes

1. 'X' means don't care.

11.4.5.1 Operation in Run Mode

As shown in Table 11-38, only MSCAN sleep mode is available as low power option when the CPU is in run mode.

11.4.5.2 Operation in Wait Mode

The WAI instruction puts the MCU in a low power consumption stand-by mode. If the CSWAI bit is set, additional power can be saved in power down mode because the CPU clocks are stopped. After leaving this power down mode, the MSCAN restarts and enters normal mode again.

While the CPU is in wait mode, the MSCAN can be operated in normal mode and generate interrupts (registers can be accessed via background debug mode).

11.4.5.3 Operation in Stop Mode

The STOP instruction puts the MCU in a low power consumption stand-by mode. In stop mode, the MSCAN is set in power down mode regardless of the value of the SLPRQ/SLPAK and CSWAI bits (Table 11-38).

11.4.5.4 MSCAN Normal Mode

This is a non-power-saving mode. Enabling the MSCAN puts the module from disabled mode into normal mode. In this mode the module can either be in initialization mode or out of initialization mode. See Section 11.4.4.5, "MSCAN Initialization Mode".



11.4.7.3 Receive Interrupt

A message is successfully received and shifted into the foreground buffer (RxFG) of the receiver FIFO. This interrupt is generated immediately after receiving the EOF symbol. The RXF flag is set. If there are multiple messages in the receiver FIFO, the RXF flag is set as soon as the next message is shifted to the foreground buffer.

11.4.7.4 Wake-Up Interrupt

A wake-up interrupt is generated if activity on the CAN bus occurs during MSCAN sleep or power-down mode.

NOTE

This interrupt can only occur if the MSCAN was in sleep mode (SLPRQ = 1 and SLPAK = 1) before entering power down mode, the wake-up option is enabled (WUPE = 1), and the wake-up interrupt is enabled (WUPIE = 1).

11.4.7.5 Error Interrupt

An error interrupt is generated if an overrun of the receiver FIFO, error, warning, or bus-off condition occurrs. MSCAN Receiver Flag Register (CANRFLG) indicates one of the following conditions:

- **Overrun** An overrun condition of the receiver FIFO as described in Section 11.4.2.3, "Receive Structures," occurred.
- CAN Status Change The actual value of the transmit and receive error counters control the CAN bus state of the MSCAN. As soon as the error counters skip into a critical range (Tx/Rxwarning, Tx/Rx-error, bus-off) the MSCAN flags an error condition. The status change, which caused the error condition, is indicated by the TSTAT and RSTAT flags (see Section 11.3.2.5, "MSCAN Receiver Flag Register (CANRFLG)" and Section 11.3.2.6, "MSCAN Receiver Interrupt Enable Register (CANRIER)").

11.4.7.6 Interrupt Acknowledge

Interrupts are directly associated with one or more status flags in either the MSCAN Receiver Flag Register (CANRFLG) or the MSCAN Transmitter Flag Register (CANTFLG). Interrupts are pending as long as one of the corresponding flags is set. The flags in CANRFLG and CANTFLG must be reset within the interrupt handler to handshake the interrupt. The flags are reset by writing a 1 to the corresponding bit position. A flag cannot be cleared if the respective condition prevails.

NOTE

It must be guaranteed that the CPU clears only the bit causing the current interrupt. For this reason, bit manipulation instructions (BSET) must not be used to clear interrupt flags. These instructions may cause accidental clearing of interrupt flags which are set after entering the current interrupt service routine.





12.3 **Register Definition**

This section consists of register descriptions in address order of the PIT. Each description includes a standard register diagram with an associated figure number. Details of register bit and field function follow the register diagrams, in bit order.

Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0000	R	PITE	PITSWAI	PITER7	0	0	0	0	0
PIICFLMI	W		1110177					PFLMT1	PFLMT0
0x0001	R	0	0	0	0	0	0	0	0
PITFLT	W					PFLT3	PFLT2	PFLT1	PFLT0
0x0002	R	0	0	0	0	DOES	DOED		DOED
PITCE	w					PCES	PGEZ	PCET	PCEU
0x0003	R	0	0	0	0		DMUNO		DMUNO
PITMUX	w					PMUX3	PMUX2	PMUX1	PMUXU
0x0004	R	0	0	0	0	DINITEO	DINITEO		
PITINTE	w					PINTE3	PINTE2	PINTE1	PINTEO
0x0005	R	0	0	0	0	DTEO	DTEO	DTEA	DTEO
PITTF	w					PIF3	PTFZ	PIFI	PIFU
0x0006	R								
PITMTLD0	W	PIVITLD7	PINITLDO	PMILD5	PIMITLD4	PINILD3	PMILDZ	PMILDI	PINITLDU
0x0007	R								
PITMTLD1	w	PIVITLD7	PINITLDO	PMILD5	PIMITLD4	PINILD3	PMILDZ	PMILDI	PINITLDU
0x0008	R								
PITLD0 (High)	w	PLD15	PLD14	PLD13	PLD12	PLDTI	PLDIU	PLD9	PLDo
0x0009	R								
PITLD0 (Low)	w	PLD7	PLD6	PLD5	PLD4	PLD3	PLDZ	PLDI	PLDU
0x000A	R			DONITAD	DONIT40	DONIT44	DONITAO	DONTO	DONITO
PITCNT0 (High)	w	PUNTIS	PCN114	PCN113	PCNT12	PCNTT	PCNTTU	PCNT9	PCN18
0x000B	R	DONTZ	DONTO	DONITO	DONT4	DONTO	DONTO	DONIT4	DONITO
PITCNT0 (Low)	w	PCNT	PCNT6	PCNT5	PCN14	PCN13	PCNT2	PCNT	PCNTU
0x000C	R								
PITLD1 (High)	w	PLD15	PLD14	PLD13	PLD12	PLD11	PLD10	PLD9	PLD8
	ſ		= Unimplemented or Reserved						

Figure 12-2. PIT Register Summary (Sheet 1 of 2)



Pulse-Width Modulator (S12PWM8B8CV1)

Clock A is used as an input to an 8-bit down counter. This down counter loads a user programmable scale value from the scale register (PWMSCLA). When the down counter reaches one, a pulse is output and the 8-bit counter is re-loaded. The output signal from this circuit is further divided by two. This gives a greater range with only a slight reduction in granularity. Clock SA equals clock A divided by two times the value in the PWMSCLA register.

NOTE

Clock SA = Clock A / (2 * PWMSCLA)

When PWMSCLA =\$00, PWMSCLA value is considered a full scale value of 256. Clock A is thus divided by 512.

Similarly, clock B is used as an input to an 8-bit down counter followed by a divide by two producing clock SB. Thus, clock SB equals clock B divided by two times the value in the PWMSCLB register.

NOTE

Clock SB = Clock B / (2 * PWMSCLB)

When PWMSCLB =\$00, PWMSCLB value is considered a full scale value of 256. Clock B is thus divided by 512.

As an example, consider the case in which the user writes \$FF into the PWMSCLA register. Clock A for this case will be E divided by 4. A pulse will occur at a rate of once every 255x4 E cycles. Passing this through the divide by two circuit produces a clock signal at an E divided by 2040 rate. Similarly, a value of \$01 in the PWMSCLA register when clock A is E divided by 4 will produce a clock at an E divided by 8 rate.

Writing to PWMSCLA or PWMSCLB causes the associated 8-bit down counter to be re-loaded. Otherwise, when changing rates the counter would have to count down to \$01 before counting at the proper rate. Forcing the associated counter to re-load the scale register value every time PWMSCLA or PWMSCLB is written prevents this.

NOTE

Writing to the scale registers while channels are operating can cause irregularities in the PWM outputs.

13.4.1.3 Clock Select

Each PWM channel has the capability of selecting one of two clocks. For channels 0, 1, 4, and 5 the clock choices are clock A or clock SA. For channels 2, 3, 6, and 7 the choices are clock B or clock SB. The clock selection is done with the PCLKx control bits in the PWMCLK register.

NOTE

Changing clock control bits while channels are operating can cause irregularities in the PWM outputs.

Table 14-4. SCICR1 Field Descriptions (continued)

Field	Description
2 ILT	 Idle Line Type Bit — ILT determines when the receiver starts counting logic 1s as idle character bits. The counting begins either after the start bit or after the stop bit. If the count begins after the start bit, then a string of logic 1s preceding the stop bit may cause false recognition of an idle character. Beginning the count after the stop bit avoids false idle character recognition, but requires properly synchronized transmissions. Idle character bit count begins after stop bit
1 PE	 Parity Enable Bit — PE enables the parity function. When enabled, the parity function inserts a parity bit in the most significant bit position. 0 Parity function disabled 1 Parity function enabled
0 PT	 Parity Type Bit — PT determines whether the SCI generates and checks for even parity or odd parity. With even parity, an even number of 1s clears the parity bit and an odd number of 1s sets the parity bit. With odd parity, an odd number of 1s clears the parity bit and an even number of 1s sets the parity bit. 0 Even parity 1 Odd parity

Table 14-5. Loop Functions

LOOPS	RSRC	Function
0	х	Normal operation
1	0	Loop mode with transmitter output internally connected to receiver input
1	1	Single-wire mode with TXD pin connected to receiver input



Serial Peripheral Interface (S12SPIV5)

15.3.2.3 SPI Baud Rate Register (SPIBR)

Module Base +0x0002



Figure 15-5. SPI Baud Rate Register (SPIBR)

Read: Anytime

Write: Anytime; writes to the reserved bits have no effect

Table	15-6.	SPIBR	Field	Descri	ptions
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Field	Description
6–4 SPPR[2:0]	SPI Baud Rate Preselection Bits — These bits specify the SPI baud rates as shown in Table 15-7. In master mode, a change of these bits will abort a transmission in progress and force the SPI system into idle state.
2–0 SPR[2:0]	SPI Baud Rate Selection Bits — These bits specify the SPI baud rates as shown in Table 15-7. In master mode, a change of these bits will abort a transmission in progress and force the SPI system into idle state.

The baud rate divisor equation is as follows:

BaudRateDivisor = (SPPR + 1) • 2 ^(SPR + 1)	Eqn. 15-1

The baud rate can be calculated with the following equation:

Baud Rate = BusClock / BaudRateDivisor

Eqn. 15-2

NOTE

For maximum allowed baud rates, please refer to the SPI Electrical Specification in the Electricals chapter of this data sheet.

Table 15-7. Example SPI Baud Rate Selection (25 MHz Bus Clock) (Sheet 1 of 3)

SPPR2	SPPR1	SPPR0	SPR2	SPR1	SPR0	Baud Rate Divisor	Baud Rate
0	0	0	0	0	0	2	12.5 Mbit/s
0	0	0	0	0	1	4	6.25 Mbit/s
0	0	0	0	1	0	8	3.125 Mbit/s
0	0	0	0	1	1	16	1.5625 Mbit/s
0	0	0	1	0	0	32	781.25 kbit/s
0	0	0	1	0	1	64	390.63 kbit/s
0	0	0	1	1	0	128	195.31 kbit/s
0	0	0	1	1	1	256	97.66 kbit/s
0	0	1	0	0	0	4	6.25 Mbit/s
0	0	1	0	0	1	8	3.125 Mbit/s
0	0	1	0	1	0	16	1.5625 Mbit/s
0	0	1	0	1	1	32	781.25 kbit/s

PAD





Figure 16-4. Channel 7 Output Compare/Pulse Accumulator Logic

16.2 External Signal Description

The TIM16B8CV2 module has a total of eight external pins.

16.2.1 IOC7 — Input Capture and Output Compare Channel 7 Pin

This pin serves as input capture or output compare for channel 7. This can also be configured as pulse accumulator input.

16.2.2 IOC6 — Input Capture and Output Compare Channel 6 Pin

This pin serves as input capture or output compare for channel 6.

16.2.3 IOC5 — Input Capture and Output Compare Channel 5 Pin

This pin serves as input capture or output compare for channel 5.

16.2.4 IOC4 — Input Capture and Output Compare Channel 4 Pin

This pin serves as input capture or output compare for channel 4. Pin

16.2.5 IOC3 — Input Capture and Output Compare Channel 3 Pin

This pin serves as input capture or output compare for channel 3.

16.2.6 IOC2 — Input Capture and Output Compare Channel 2 Pin

This pin serves as input capture or output compare for channel 2.



256 KByte Flash Module (S12XFTMR256K1V1)

OSCCLK Frequency (MHz)		FDIV[6:0]	OSCCLK (M	FDIV[6:0]	
MIN ¹	MAX ²		MIN ¹	MAX ²	
1.60	2.10	0x01	33.60	34.65	0x20
2.40	3.15	0x02	34.65	35.70	0x21
3.20	4.20	0x03	35.70	36.75	0x22
4.20	5.25	0x04	36.75	37.80	0x23
5.25	6.30	0x05	37.80	38.85	0x24
6.30	7.35	0x06	38.85	39.90	0x25
7.35	8.40	0x07	39.90	40.95	0x26
8.40	9.45	0x08	40.95	42.00	0x27
9.45	10.50	0x09	42.00	43.05	0x28
10.50	11.55	0x0A	43.05	44.10	0x29
11.55	12.60	0x0B	44.10	45.15	0x2A
12.60	13.65	0x0C	45.15	46.20	0x2B
13.65	14.70	0x0D	46.20	47.25	0x2C
14.70	15.75	0x0E	47.25	48.30	0x2D
15.75	16.80	0x0F	48.30	49.35	0x2E
16.80	17.85	0x10	49.35	50.40	0x2F
17.85	18.90	0x11			
18.90	19.95	0x12			
19.95	21.00	0x13			
21.00	22.05	0x14			
22.05	23.10	0x15			
23.10	24.15	0x16			
24.15	25.20	0x17			
25.20	26.25	0x18			
26.25	27.30	0x19			
27.30	28.35	0x1A			
28.35	29.40	0x1B			
29.40	30.45	0x1C			
30.45	31.50	0x1D			
31.50	32.55	0x1E			
32.55	33.60	0x1F			

Table 18-7. FDIV vs OSCCLK Frequency

¹ FDIV shown generates an FCLK frequency of >0.8 MHz

² FDIV shown generates an FCLK frequency of 1.05 MHz



256 KByte Flash Module (S12XFTMR256K1V1)

Table 18-3). The Verify Backdoor Access Key command must not be executed from the Flash block containing the backdoor comparison key to avoid code runaway.

CCOBIX[2:0]	FCCOB Parameters				
000	0x0C Not required				
001	Key 0				
010	Key 1				
011	Key 2				
100	Key 3				

Table 18-51. Verify Backdoor Access Key Command FCCOB Requirements

Upon clearing CCIF to launch the Verify Backdoor Access Key command, the Memory Controller will check the FSEC KEYEN bits to verify that this command is enabled. If not enabled, the Memory Controller sets the ACCERR bit in the FSTAT register and terminates. If the command is enabled, the Memory Controller compares the key provided in FCCOB to the backdoor comparison key in the Flash configuration field with Key 0 compared to 0x7F_FF00, etc. If the backdoor keys match, security will be released. If the backdoor keys do not match, security is not released and all future attempts to execute the Verify Backdoor Access Key command are aborted (set ACCERR) until a reset occurs. The CCIF flag is set after the Verify Backdoor Access Key operation has completed.

Table 18-52. Verify Backdoor Access Key Command Error Handling

Register	Error Bit	Error Condition				
		Set if CCOBIX[2:0] != 100 at command launch				
		Set if an incorrect backdoor key is supplied				
	ACCERR	Set if backdoor key access has not been enabled (KEYEN[1:0] != 10, see Section 18.3.2.2)				
FSTAT		Set if the backdoor key has mismatched since the last reset				
	FPVIOL	None				
	MGSTAT1	None				
	MGSTAT0	None				

18.4.2.12 Set User Margin Level Command

The Set User Margin Level command causes the Memory Controller to set the margin level for future read operations of a specific P-Flash or D-Flash block.

Table 18-53. Set User Margin Leve	I Command FCCOB Requirements
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CCOBIX[2:0]	FCCOB Parameters				
000	0x0D	Global address [22:16] to identify the Flash block			
001	Margin level setting				



Electrical Characteristics

is recommended to configure PortAD pins as outputs only for low frequency, low load outputs. The impact on ATD accuracy is load dependent and not specified. The values specified are valid under condition that no PortAD output drivers switch during conversion.

A.2.2.2 Source Resistance

Due to the input pin leakage current as specified in Table A-7 and Table A-8 in conjunction with the source resistance there will be a voltage drop from the signal source to the ATD input. The maximum source resistance R_S specifies results in an error (10-bit resolution) of less than 1/2 LSB (2.5 mV) at the maximum leakage current. If device or operating conditions are less than worst case or leakage-induced error is acceptable, larger values of source resistance of up to 10Kohm are allowed.

A.2.2.3 Source Capacitance

When sampling an additional internal capacitor is switched to the input. This can cause a voltage drop due to charge sharing with the external and the pin capacitance. For a maximum sampling error of the input voltage ≤ 1 LSB (10-bit resilution), then the external filter capacitor, $C_f \geq 1024 * (C_{INS}-C_{INN})$.

A.2.2.4 Current Injection

There are two cases to consider.

- 1. A current is injected into the channel being converted. The channel being stressed has conversion values of \$3FF (in 10-bit mode) for analog inputs greater than V_{RH} and \$000 for values less than V_{RL} unless the current is higher than specified as disruptive condition.
- 2. Current is injected into pins in the neighborhood of the channel being converted. A portion of this current is picked up by the channel (coupling ratio K), This additional current impacts the accuracy of the conversion depending on the source resistance.

The additional input voltage error on the converted channel can be calculated as:

 $V_{ERR} = K * R_S * I_{INJ}$

with I_{INJ} being the sum of the currents injected into the two pins adjacent to the converted channel.



Package Information





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TITLE: 112LD LQFP		DOCUMENT NO	: 98ASS23330W	REV: F
20 X 20 X 1.4		CASE NUMBER	2: 987–03	15 DEC 2006
0.65 PITCH		STANDARD: JE	DEC MS-026 BFA	

Figure B-2. 112-pin LQFP (case no. 987) - page 2